The HD74LS374, 8-bit registers features totem-pole three-state outputs designed specifically for driving highly-capacitive or relatively low-impedance foads. The high-impedance third state and increased high-logic-level drive provide this register with the capability of being connected directly to and driving the bus lines in a bus-organized system without need for interface or pull-up components. They are particularly attractive for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. The eight flip-flops are edge-triggered D-type flip-flops. On the positive transition the clock, the Q outputs will be set to the logic states that were setup at the D inputs,

EFUNCTION TABLE

	Output		
Output control	Clock	Ð	Q
L	Ť	Н	Н
L	1	L	L
L	L	×	\mathbf{Q}_0
Н	×	×	Z

Notes:

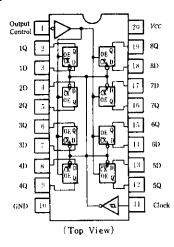
H = high level, L = low level, X = irrelevant

= transition from low to

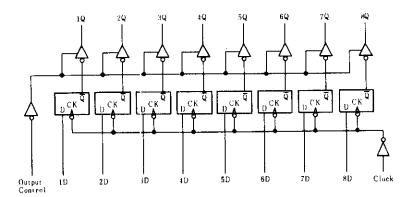
high level
Q0 = level of Q before the indicated steady-state input conditions were

z = established
z = off (high-impedance)
state of a three-state
output

MPIN ARRANGEMENT



BLOCK DIAGRAM



MRECOMMENDED OPERATING CONDITION

Iten)	Symbol	min	typ	max	Unit	
Supply voltage		Vcc	4.75	5.00	5.26	V	
Output voltage		Voн		_	5.5	V	
Output current		Іон			-2.6	mA	
		Ioz			24	mA	
Clock pulse "H" level			15	_	_		
width	"L" level	tw.	15	_	_	ns	
Data setup time	,	Lou	20 †	_		ns	
Data hold time		t h	3 †		_	ns	

Note) † : The arrow indicates the rising edge of clock pulse.

TELECTRICAL CHARACTERISTICS $(Ta = -20 \sim +75^{\circ}\text{C})$

Item	Symbol	Test Condi	min	typ*	max	Unit	
T	V_{IH}			2.0		-	V
Input voltage	V_{IL}			-		0.8	V
	Van	$V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V}, V_{IL} = 0$.8V, I _{OH} == -2.6mA	2.4			V
Output voltage	Vol	$V_{CC} = 4.75 \text{V}, V_{IH} = 2 \text{V},$ $V_{IL} = 0.8 \text{V}$	IoL = 12mA			0.4	v
			Iot - 24mA	****		0.5	
Off-state output current	Iozн	$V_{CC} = 5.25 \text{V}. V_{CH} = 2 \text{V}$	$V_o = 2.7 \text{V}$		-	20	μA
	lozi	$V_{CC} = 5.25 \text{ V}, V_{IH} = 2 \text{ V}$	$V_o = 0.4 \text{V}$			20	
	I_{IH}	$V_{CC} = 5.25 \text{V}, V_I = 2.7 \text{V}$				20	μA
Input current	I_{IL}	$V_{CC} = 5.25 \text{V}, V_I = 0.4 \text{V}$	_]	_	-0.4	mA	
	I_{I}	$V_{cc} = 5.25$ V. $V_i = 7$ V			0.1	mA	
Short-circuit output current	Ios	$V_{CC}=5.25V$	30	-	-130	mA	
Supply current	I_{cc}	$V_{CC} = 5.25V$, $V_I = 4.5V$ (C	Output control)		27	40	mA
Input clamp voltage	V_{IK}	$V_{CC}=4.75$ V, $I_{IN}=-18$ mA		-	-1.5	V	

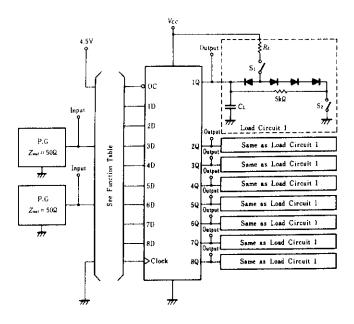
^{*} VCC=5V, Ta=25°C

ESWITCHING CHARACTERISTICS $(V_{cc}=5V, T_a=25^{\circ}C)$

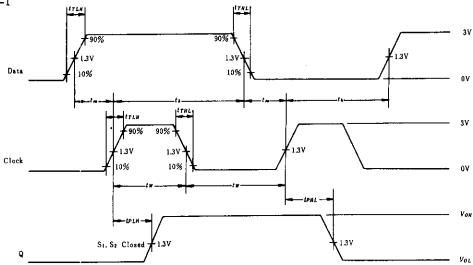
Item	Symbol	Inputs	Outputs	Test Conditions	min	typ	max	Unit	
Maximum clock frequency	f	Clock	Q		35	50	-	MHz	
December 1.1 . 4.1	tpln	Clock	Q	$C_{t} = 45 \text{pF}$ $R_{L} = 667 \Omega$	-	15	28	ns	
Propagation delay time	t_{PHL}					19	28		
O-44	l _{ZH}	ос	Q		-	20	28		
Output enable time	tzi					21	28		
Output disable time $ \frac{t_{HZ}}{t_{LZ}} = 0 $	00	000	$C_L = 5pF$		12	20			
			UC Q	UC	Q	$R_{\perp} = 667\Omega$		14	25

TESTING METHOD

Test Circuit



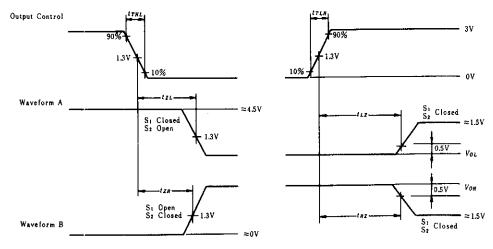
Waveform-1



Notes:

- Input pulse; t_{TLH} = 15ns, t_{THL} = 6ns Clock input; PRR = 1MHz, duty cycle 50% Data input; PRR = 500kHz, duty cycle 50%
 f_{max}; t_{TLH} = 2.5ns, t_{THL} = 2.5ns

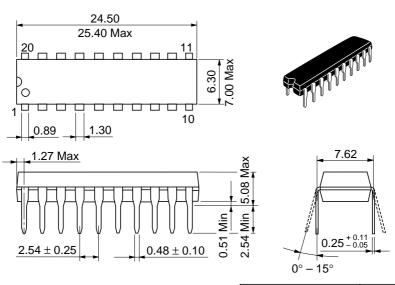
Waveform-2



1. Input pulse; $t_{TLH} = 15$ ns, $t_{THL} = 6$ ns, PRR = 1MHz, duty cycle 50% Notes:

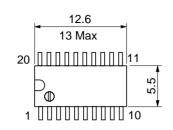
2. Waveform A is for an output with internal conditions such that the output is low except when disable by the output control. Waveform B is for an output with internal conditions such that the output is high except when disabled by the output control.

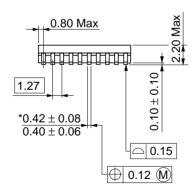
Unit: mm

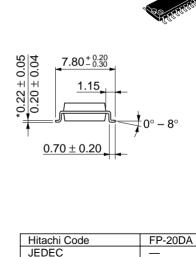


Hitachi Code	DP-20N
JEDEC	_
EIAJ	Conforms
Weight (reference value)	1.26 g

Unit: mm







Weight (reference value)

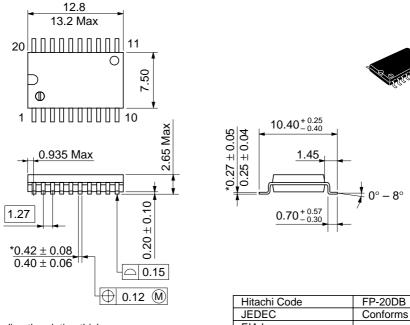
Conforms

0.31 g

EIAJ

*Dimension including the plating thickness
Base material dimension

Unit: mm



*Dimension including the plating thickness

Base material dimension

*EIAJ

Weight (reference value) 0.52 g

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